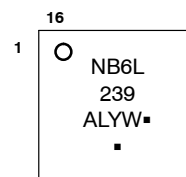
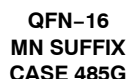


2.5V / 3.3V Any Differential Clock IN to Differential LVPECL OUT $\div 1/2/4/8$, $\div 2/4/8/16$ Clock Divider



Description

MARKING DIAGRAM*



A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

Features

- Maximum Clock Input Frequency, 3.0 GHz
- CLOCK Inputs Compatible with LVDS/LVPECL/CML/HSTL/HCSL
- $\overline{\text{EN}}$, $\overline{\text{MR}}$, and SEL Inputs Compatible with LVTTTL/LVCMOS
- Rise/Fall Time 65 ps Typical
- < 10 ps Typical Output-to-Output Skew
- Example: 622.08 MHz Input Generates 38.88 MHz to 622.08 MHz Outputs
- Internal 50 Ω Termination Provided
- Random Clock Jitter < 1 ps RMS
- QA $\div$ 1 Edge Aligned to QB $\div$ n Edge
- Operating Range: $V_{\text{CC}} = 2.375 \text{ V}$ to 3.465 V with $V_{\text{EE}} = 0 \text{ V}$
- Master Reset for Synchronization of Multiple Chips
- V_{BBAC} Reference Output
- Synchronous Output Enable/Disable
- These Devices are Pb-Free and are RoHS Compliant

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 11 of this data sheet.

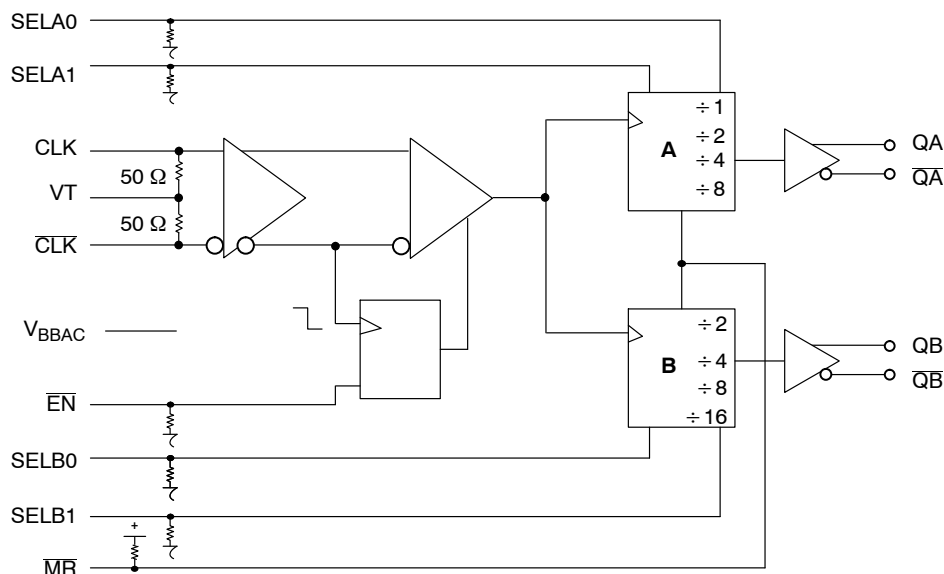


Figure 1. Simplified Logic Diagram

NB6L239

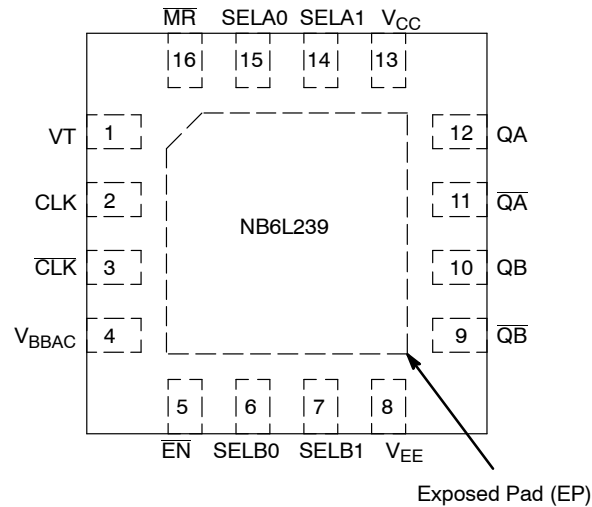


Figure 2. Pinout: QFN-16 (Top View)

Table 1. PIN DESCRIPTION

Pin	Name	I/O	Description
1	VT		Internal 100 Ω Center-Tapped Termination Pin for CLK and $\overline{\text{CLK}}$.
2	CLK	LVPECL, CML, LVDS, HCSL, HSTL Input	Noninverted Differential CLOCK Input.
3	$\overline{\text{CLK}}$	LVPECL, CML, LVDS, HCSL, HSTL Input	Inverted Differential CLOCK Input.
4	V_{BBAC}		Output Voltage Reference for Capacitor Coupled Inputs, Only.
5	$\overline{\text{EN}}^*$	LVC MOS/LVTTL Input	Synchronous Output Enable
6	SELB0*	LVC MOS/LVTTL Input	Clock Divide Select Pin
7	SELB1*	LVC MOS/LVTTL Input	Clock Divide Select Pin
8	V_{EE}	Power Supply	Negative Supply Voltage
9	$\overline{\text{QB}}$	LVPECL Output	Inverted Differential Output. Typically terminated with 50 Ω resistor to $V_{\text{CC}} - 2.0 \text{ V}$.
10	QB	LVPECL Output	Noninverted Differential Output. Typically terminated with 50 Ω resistor to $V_{\text{CC}} - 2.0 \text{ V}$.
11	$\overline{\text{QA}}$	LVPECL Output	Inverted Differential Output. Typically terminated with 50 Ω resistor to $V_{\text{CC}} - 2.0 \text{ V}$.
12	QA	LVPECL Output	Noninverted Differential Output. Typically terminated with 50 Ω resistor to $V_{\text{CC}} - 2.0 \text{ V}$.
13	V_{CC}	Power Supply	Positive Supply Voltage.
14	SELA1*	LVC MOS/LVTTL Input	Clock Divide Select Pin
15	SELA0*	LVC MOS/LVTTL Input	Clock Divide Select Pin
16	$\overline{\text{MR}}^{**}$	LVC MOS/LVTTL Input	Master Reset Asynchronous, Default Open High, Asserted LOW
	EP	Power Supply (OPT)	The Exposed Pad on the QFN-16 package bottom is thermally connected to the die for improved heat transfer out of package. The pad is electrically connected to the die, and is recommended to be electrically and thermally connected to V_{EE} on the PC board.

*Pins will default LOW when left OPEN.

**Pins will default HIGH when left OPEN.

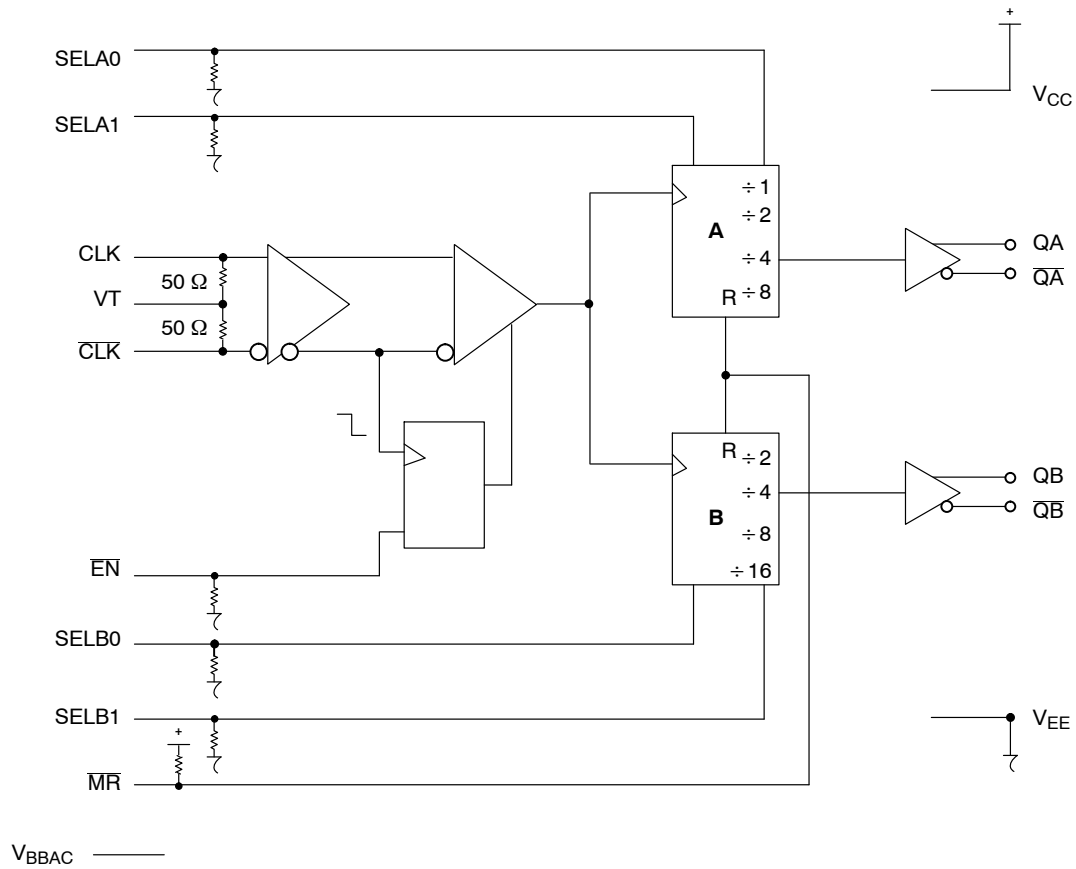
NB6L239

Figure 3. Logic Diagram

Table 2. FUNCTION TABLE

CLK	EN*	MR**	FUNCTION
	L	H	Divide
	H	H	Hold Q
X	X	L	Reset Q

Table 3. CLOCK DIVIDE SELECT, QA OUTPUTS

SELA1*	SELA0*		QA Outputs
L	L		Divide by 1
L	H		Divide by 2
H	L		Divide by 4
H	H		Divide by 8

Table 4. CLOCK DIVIDE SELECT, QB OUTPUTS

SELB1*	SELB0*		QB Outputs
L	L		Divide by 2
L	H		Divide by 4
H	L		Divide by 8
H	H		Divide by 16

┐ = Low-to-High Transition

⌋ = Low-to-High Transition
⌋ = High-to-Low Transition

X = Don't Care

*Pins will default LOW when left OPEN.

****Pins will default HIGH when left OPEN.**

Table 5. ATTRIBUTES

Characteristics	Value
Internal Input Pulldown Resistor Internal Input Pullup Resistor	75 k Ω 75 k Ω
ESD Protection Human Body Model Machine Model Charged Device Model	> 1500 V > 150 V > 1000 V
Moisture Sensitivity, Indefinite Time Out of Drypack (Note 1)	Pb-Free Pkg
QFN-16	Level 1
Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in
Transistor Count	367
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test	

1. For additional Moisture Sensitivity information, refer to Application Note AND8003/D.

MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	Positive Mode Power Supply	V _{EE} = 0 V		3.6	V
V _I	Input Voltage	V _{EE} = 0 V	V _{EE} ≤ V _I ≤ V _{CC}	3.6	V
I _{out}	Output Current	Continuous Surge		50 100	mA mA
I _{BB}	V _{BBAC} Sink/Source Current			± 0.5	mA
T _A	Operating Temperature Range			–40 to +85	°C
T _{stg}	Storage Temperature Range			–65 to +150	°C
θ _{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm		41.6 35.2	°C/W °C/W
θ _{JC}	Thermal Resistance (Junction-to-Case)	Standard Board		4.0	°C/W
T _{sol}	Wave Solder Pb-Free			265	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 6. DC CHARACTERISTICS, CLOCK INPUTS, LVPECL OUTPUTS(V_{CC} = 2.375 V to 3.465 V, V_{EE} = 0 V)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I _{EE}	Power Supply Current	30	40	50	30	40	50	30	40	50	mA
V _{OH}	Output HIGH Voltage (Notes 2, 3) V _{CC} = 3.3 V V _{CC} = 2.5 V	V _{CC} -1150 2150 1350	V _{CC} -1060 2240 1440	V _{CC} -950 2350 1550	V _{CC} -1100 2200 1400	V _{CC} -1015 2285 1485	V _{CC} - 900 2400 1600	V _{CC} -1050 2250 1450	V _{CC} - 980 2320 1520	V _{CC} - 850 2450 1650	mV
V _{OL}	Output LOW Voltage (Notes 2, 3) V _{CC} = 3.3 V V _{CC} = 2.5 V	V _{CC} -1935 1365 565	V _{CC} -1775 1525 725	V _{CC} -1630 1670 870	V _{CC} -1875 1430 630	V _{CC} -1735 1565 765	V _{CC} -1580 1720 920	V _{CC} -1810 1490 690	V _{CC} -1675 1625 825	V _{CC} -1530 1770 970	mV

DIFFERENTIAL INPUT DRIVEN SINGLE-ENDED (Figures 7, 10)

V _{th}	Input Threshold Reference Voltage (Note 4)	100		V _{CC} - 100	100		V _{CC} - 100	100		V _{CC} - 100	mV
V _{IH}	Single-ended Input HIGH Voltage	V _{th} + 100		V _{CC}	V _{th} + 100		V _{CC}	V _{th} + 100		V _{CC}	mV
V _{IL}	Single-ended Input LOW Voltage	V _{EE}		V _{th} - 100	V _{EE}		V _{th} - 100	V _{EE}		V _{th} - 100	mV
V _{BBAC}	Output Voltage Reference @ 100 μ A (Note 7) V _{CC} = 3.3 V V _{CC} = 2.5 V	V _{CC} -1460 1840 1040	V _{CC} -1330 1970 1170	V _{CC} -1200 2100 1300	V _{CC} -1460 1840 1040	V _{CC} -1340 1960 1160	V _{CC} -1200 2100 1300	V _{CC} -1460 1840 1040	V _{CC} -1350 1950 1150	V _{CC} -1200 2100 1300	mV

DIFFERENTIAL INPUT DRIVEN DIFFERENTIALLY (Figures 8, 9, 11) (Note 6)

V _{IHD}	Differential Input HIGH Voltage	100		V _{CC}	100		V _{CC}	100		V _{CC}	mV
V _{ILD}	Differential Input LOW Voltage	V _{EE}		V _{CC} - 100	V _{EE}		V _{CC} - 100	V _{EE}		V _{CC} - 100	mV
V _{CMR}	Input Common Mode Range (Differential Cross-point Voltage) (Note 5)	50		V _{CC} - 50	50		V _{CC} - 50	50		V _{CC} - 50	mV
V _{ID}	Differential Input Voltage (V _{IHD} (CLK) - V _{ILD} (CLK)) and (V _{IHD} (CLK) - V _{ILD} (CLK))	100		V _{CC} - V _{EE}	100		V _{CC} - V _{EE}	100		V _{CC} - V _{EE}	mV
R _{TIN}	Internal Input Termination Resistor	45	50	55	45	50	55	45	50	55	Ω

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- Input and output parameters vary 1:1 with V_{CC}.
- Outputs loaded with 50 Ω to V_{CC} - 2.0 V for proper operation.
- V_{th} is applied to the complementary input when operating in single-ended mode.
- V_{CMR}_{MIN} varies 1:1 with V_{EE}, V_{CMR}_{MAX} varies 1:1 with V_{CC}.
- Input and output voltage swing is a single-ended measurement operating in differential mode.
- V_{BBAC} used to rebias capacitor-coupled inputs only (see Figures 16 and 17).

Table 7. DC CHARACTERISTICS, LVTTTL/LVCMOS INPUTS ($V_{CC} = 2.375 \text{ V}$ to 3.465 V , $V_{EE} = 0 \text{ V}$, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$)

Symbol	Characteristic	Min	Typ	Max	Unit
V_{IH}	Input HIGH Voltage (LVCMOS/LVTTTL)	2.0		V_{CC}	V
V_{IL}	Input LOW Voltage (LVCMOS/LVTTTL)	V_{EE}		0.8	V
I_{IH}	Input HIGH Current	-150		150	μA
I_{IL}	Input LOW Current	-150		150	μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

Table 8. AC CHARACTERISTICS $V_{CC} = 2.375 \text{ V}$ to 3.465 V ; $V_{EE} = 0 \text{ V}$ (Note 8)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f_{inMAX}	Maximum Input CLOCK Frequency	3.0			3.0			3.0			GHz
V_{OUTPP}	Output Voltage Amplitude (Notes 10, 11)										mV
	QA ($\div 2, 4, 8$), QB ($\div n$) $f_{in} \leq 3.0 \text{ GHz}$	450	650		450	650		450	650		
	QA ($\div 1$), QB ($\div n$) $f_{in} \leq 2.5 \text{ GHz}$	450	650		450	630		450	610		
	QA ($\div 1$), QB ($\div n$) $2.5 \text{ GHz} < f_{in} \leq 3.0 \text{ GHz}$	300	650		250	650		200	650		
t_{PLH} , t_{PHL}	Propagation Delay to CLK, Qn	370	470	570	370	470	570	400	500	600	ps
	Output Differential @ 50 MHz MR, Qn	330	370	430	330	380	430	330	400	480	
t_{RR}	Reset Recovery	0	-90		0	-90		0	-90		ps
t_s	Setup Time @ 50 MHz EN, CLK	0	-60		0	-60		0	-60		ps
	SELA/B, CLK	0	-300		0	-300		0	-300		
t_h	Hold Time @ 50 MHz CLK, EN	150	65		150	65		150	65		ps
	CLK, SELA/B	700	200		700	200		700	200		
t_{skew}	Within-Device Skew @ 50 MHz (Note 9)		5	30		5	30		6	35	ps
	Device-to-Device Skew (Note 9)		25	80		30	90		30	90	
	Duty Cycle Skew (Note 9)		25	40		30	45		30	45	
t_{PW}	Minimum Pulse Width MR	550			550			550			ps
t_{JITTER}	RMS Random Clock Jitter (See Figure 20. $F_{max}/JITTER$)			< 1			< 1			< 1	ps
V_{INPP}	Input Voltage Swing (Differential Configuration) (Note 10)	100		$V_{CC} - V_{EE}$	100		$V_{CC} - V_{EE}$	100		$V_{CC} - V_{EE}$	mV
t_r , t_f	Output Rise/Fall Times @ 50 MHz (20% – 80%) Qn, Qn	30	60	120	30	65	120	30	70	120	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

8. Measured using a 750 mV, 50% duty cycle clock source. All loading with 50Ω to $V_{CC} - 2.0 \text{ V}$.

9. Skew is measured between outputs under identical transitions and conditions. Duty cycle skew is defined only for differential operation when the delays are measured from the cross point of the inputs to the cross point of the outputs.

10. Input and output voltage swing is a single-ended measurement operating in differential mode.

11. Output Voltage Amplitude ($V_{OHCLK} - V_{OLCLK}$) at input CLOCK frequency, f_{in} . The output frequency, f_{out} , is the input CLOCK frequency divided by n, $f_{out} = f_{in} \div n$. Input CLOCK frequency is $\leq 3.0 \text{ GHz}$.

Application Information

The NB6L239 is a high-speed, low skew clock divider with two divider circuits, each having selectable clock divide ratios; $\div 1/2/4/8$ and $\div 2/4/8/16$. Both divider circuits drive a pair of differential LVPECL outputs. The internal dividers are synchronous to each other. Therefore, the common output edges are precisely aligned.

The NB6L239 clock inputs can be driven by a variety of differential signal level technologies including LVDS, LVPECL, HCSL, HSTL, or CML. The differential clock input buffer employs a pair of internal $50\ \Omega$ termination resistors in a $100\ \Omega$ center-tapped configuration and accessible via the VT pin. This feature provides transmission line termination on-chip, at the receiver end, eliminating external components. The V_{BBAC} reference output can be used to rebias capacitor-coupled

differential or single-ended input CLOCK signals. For the capacitor-coupled CLK and/or $\overline{CLK}$ inputs, V_{BBAC} should be connected to the V_T pin and bypassed to ground with a $0.01\ \mu F$ capacitor. Inputs CLK and $\overline{CLK}$ must be signal driven or auto oscillation may result.

The common enable ($\overline{EN}$) is synchronous so that the internal divider flip-flops will only be enabled/disabled when the internal clock is in the LOW state. This avoids any chance of generating a runt pulse on the internal clock when the device is enabled/disabled, as can happen with an asynchronous control. The internal enable flip-flop is clocked on the falling edge of the input clock. Therefore, all associated specification limits are referenced to the negative edge of the clock input.

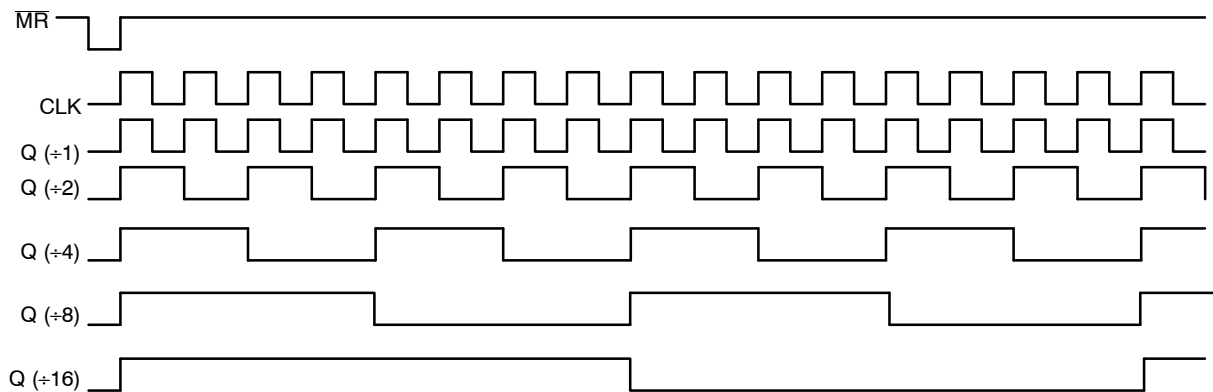


Figure 4. Timing Diagram

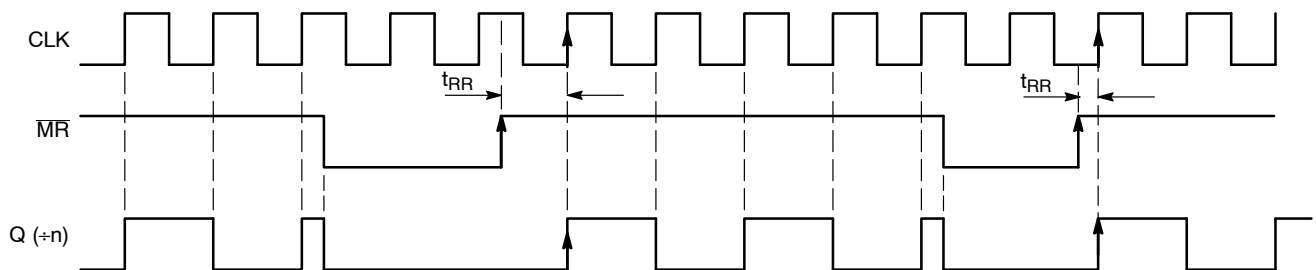


Figure 5. Master Reset Timing Diagram

NOTE: On the rising edge of $\overline{MR}$, Q goes HIGH after the first rising edge of CLK.

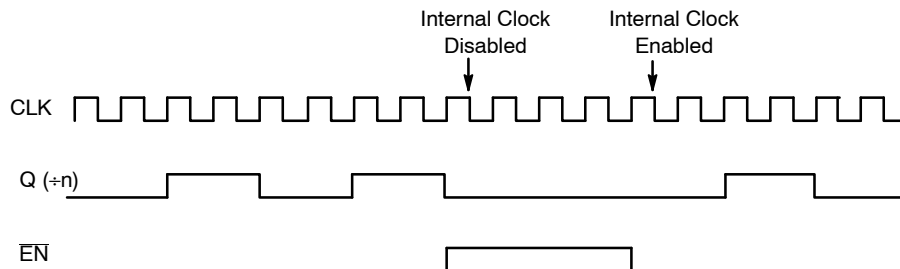


Figure 6. Output Enable Timing Diagrams

The $\overline{EN}$ signal will “freeze” the internal divider flip-flops on the first falling edge of CLK after its assertion. The internal divider flip-flops will maintain their state during the freeze. When $\overline{EN}$ is deasserted (LOW), and after the next falling edge of CLK, then the internal divider flip-flops will “unfreeze” and continue to their next state count with proper phase relationships.

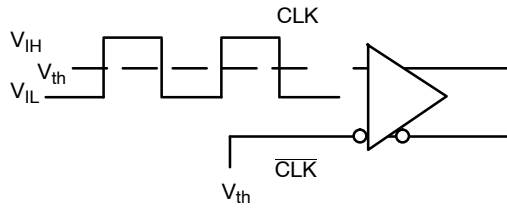


Figure 7. Differential Input Driven Single-Ended

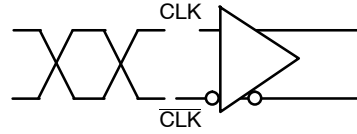


Figure 8. Differential Inputs Driven Differentially

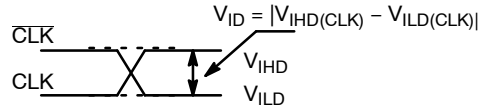


Figure 9. Differential Inputs Driven Differentially

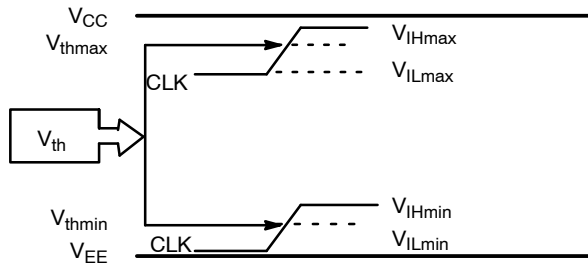


Figure 10. V_{th} Diagram

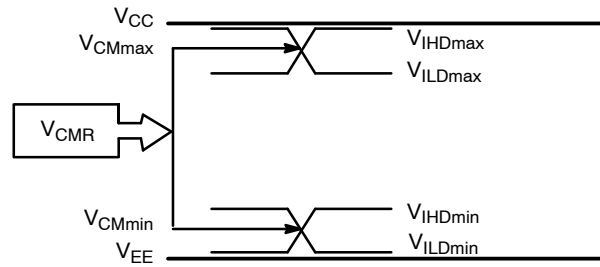


Figure 11. V_{CM} Diagram

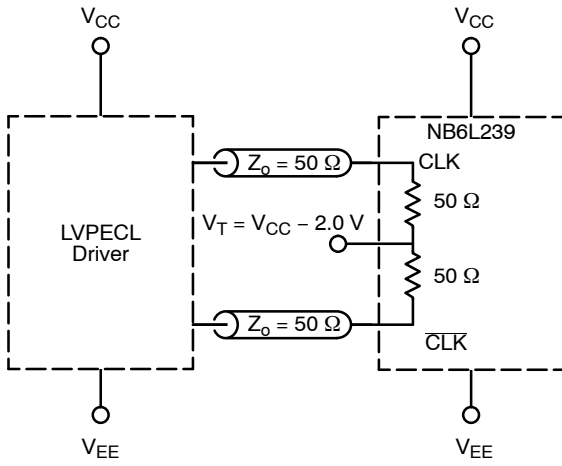


Figure 12. LVPECL Interface

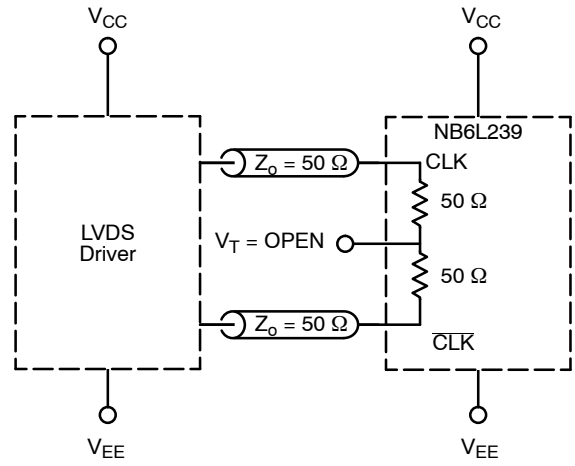


Figure 13. LVDS Interface

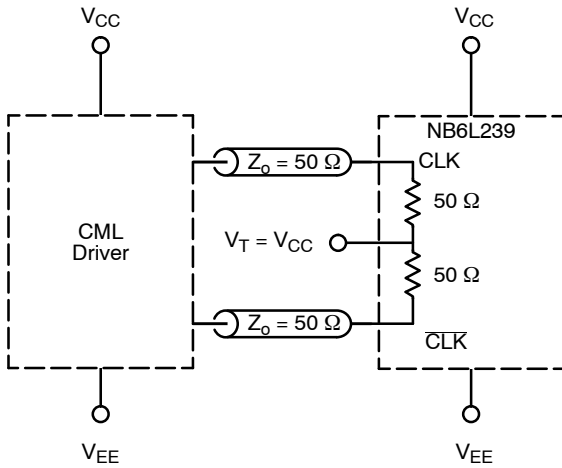


Figure 14. Standard 50 Ω Load CML Interface

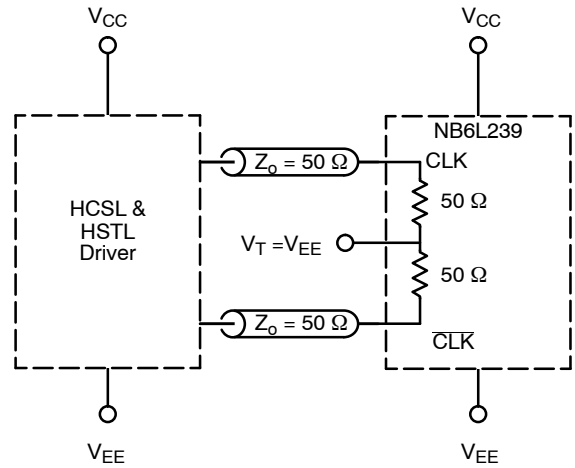


Figure 15. Standard 50 Ω Load HCSL & HSTL Interface

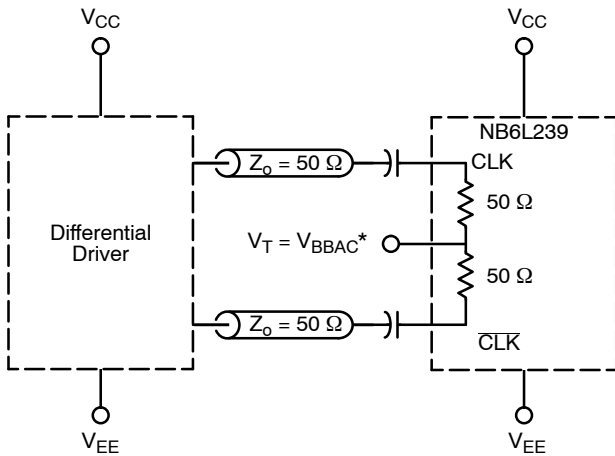


Figure 16. Capacitor-Coupled Differential Interface (V_T Connected to V_{BBAC})

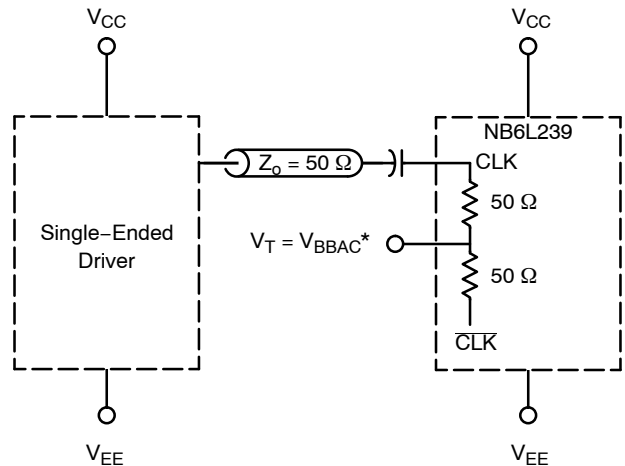


Figure 17. Capacitor-Coupled Single-Ended Interface (V_T Connected to V_{BBAC})

* V_{BBAC} bypassed to ground with a 0.01 μF capacitor.

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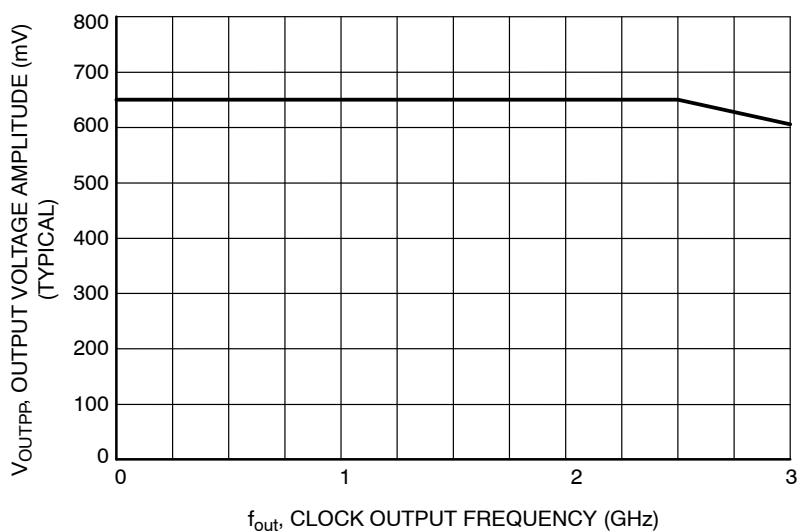


Figure 18. Output Voltage Amplitude (V_{OUTPP}) versus Clock Output Frequency at Ambient Temperature (Typical) (f_{OUT} QA/QB) = f_{IN} ÷ n; f_{IN} ≤ 3.0 GHz).

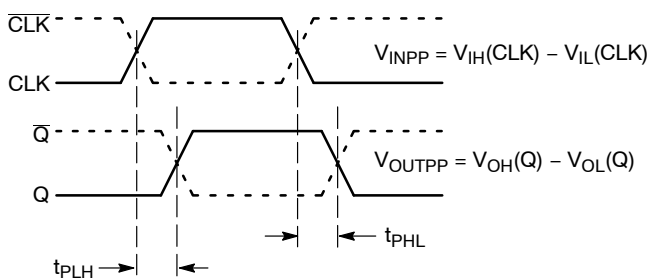


Figure 19. AC Reference Measurement

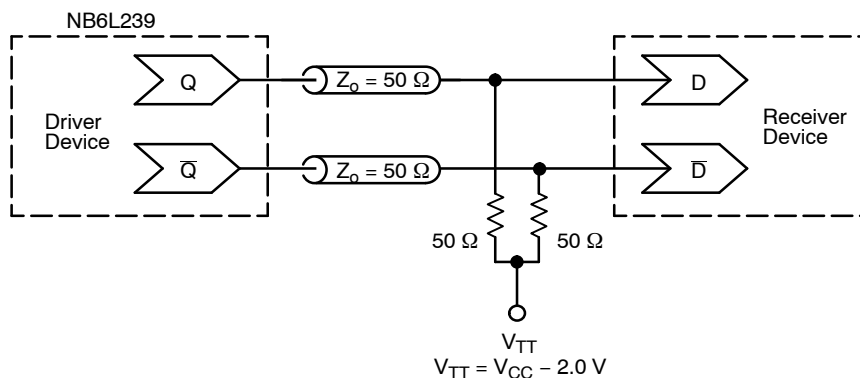


Figure 20. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices.)

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ORDERING INFORMATION

Device	Package	Shipping [†]
NB6L239MNG	QFN-16, 3 x 3 mm (Pb-Free)	123 Units / Rail
NB6L239MNR2G	QFN-16, 3 x 3 mm (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

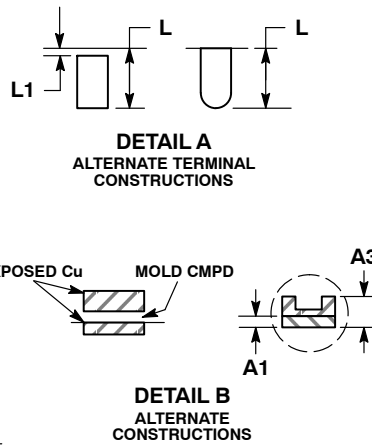
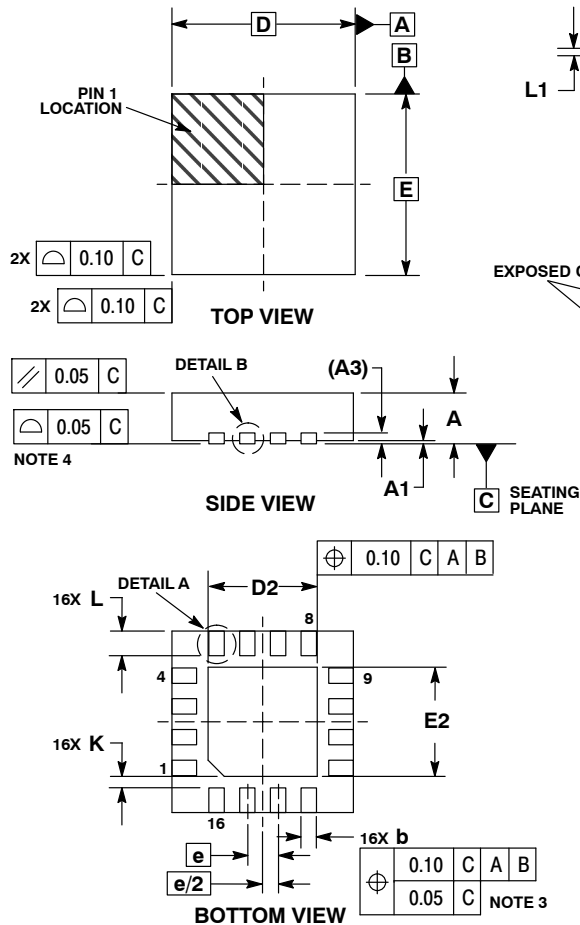
Resource Reference of Application Notes

- AN1405/D** – ECL Clock Distribution Techniques
- AN1406/D** – Designing with PECL (ECL at +5.0 V)
- AN1503/D** – ECLinPS I/O SPiCE Modeling Kit
- AN1504/D** – Metastability and the ECLinPS Family
- AN1568/D** – Interfacing Between LVDS and ECL
- AN1672/D** – The ECL Translator Guide
- AND8001/D** – Odd Number Counters Design
- AND8002/D** – Marking and Date Codes
- AND8020/D** – Termination of ECL Logic Devices
- AND8066/D** – Interfacing with ECLinPS
- AND8090/D** – AC Characteristics of ECL Devices

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PACKAGE DIMENSIONS

QFN16 3x3, 0.5P
CASE 485G
ISSUE F

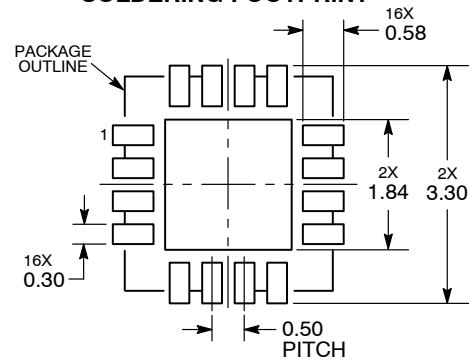


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.80	0.90	1.00
A1	0.00	0.03	0.05
A3	0.20 REF		
b	0.18	0.24	0.30
D	3.00 BSC		
D2	1.65	1.75	1.85
E	3.00 BSC		
E2	1.65	1.75	1.85
e	0.50 BSC		
K	0.18 TYP		
L	0.30	0.40	0.50
L1	0.00	0.08	0.15

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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